

Abstract of the Disclosure

A compensating blister die cutter apparatus is disclosed which has the purpose of cutting a sheet of blisters which have been formed on a sheet of plastic material in individual blisters which are generally symmetrical in configuration. The apparatus includes at least first and second blister die cutter units supported by a base member. Each of the blister die cutter units comprises a supporting member which includes a bottom board, a backup plate positioned on the bottom board, and a top board positioned on the backup plate. A rule slot is provided in the top board and a steel rule is located in the rule slot and has a cutting edge. A cavity is formed in the central portion of the bottom board, backup plate and top board as assembled to accommodate the blister shape during the cutting operation. A threaded member connects the bottom board, backup plate and top board together to move as a unit. Vertical holes extend through the connected bottom board, backup plate and top board and have a diameter of a given dimension through which adjustment members extend which are threaded into the base member. The adjustment members have a smaller diameter than the given dimension thus permitting lateral movement of the connected bottom board, backup plate and top board relative to said base member.